

## EVG BOND & ALIGNMENT SYSTEM

 Villach

### BRIEF DESCRIPTION

Bond alignment system for universal alignment with proprietary method for micron-level face-to-face wafer alignment.

### RESEARCH SERVICES

- Wafer bonding with both optical and mechanical alignment systems
- Anodic bonding, adhesive bonding, metallic bonding, glass frit bonding, etc.
- Double & triple stack Wafer-to-Wafer bonding
- Temporary bonding
- From 4" to 8" wafer sizes
- Wafer bond analysis, bond strength measurement, etc.
- 3D integration via collective Chip 2 Wafer bonding
- Hermetic wafer bonding (bonding under high vacuum, N<sub>2</sub>, Ar, CO<sub>2</sub>, etc)
- Wafer preparation & pre-processing for wafer bonds including bond frame micro-fabrication

### METHODS & EXPERTISE ON THE RESEARCH INFRASTRUCTURE

The EVG bond alignment systems are qualified throughout production environments and offer the highest precision, flexibility and ease of use, and modular upgrade capability. The precision of the bond aligners accommodates the most demanding alignment processes.

### CONTACT

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